

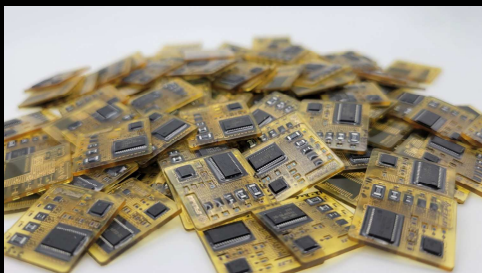
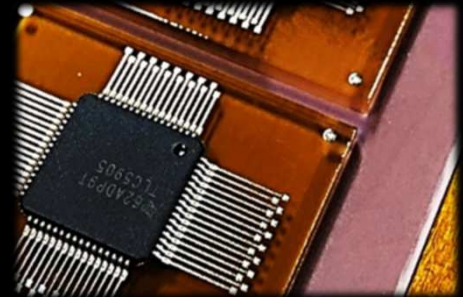
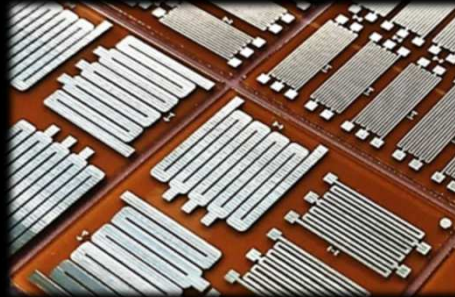
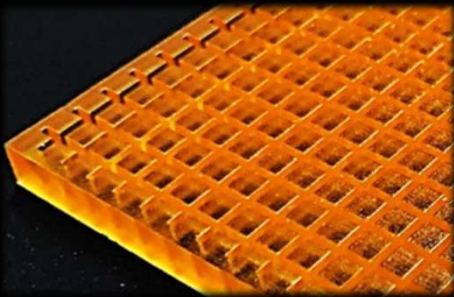
FPM-Trinity



Resin printing

Conductive printing

Parts mounting



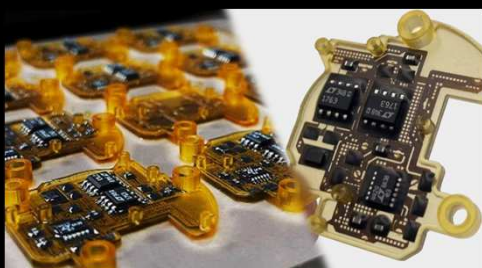
Rapid manufacturing

Electronic devices can be manufactured in a single day, accelerating prototyping.



Minimum waste

Additive manufacturing process drastically reduces liquid and material waste.



3D free shape electronics

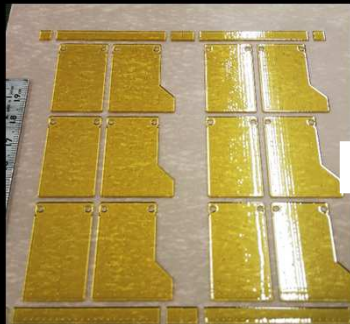
FPM-Trinity can make devices of ideal shapes.

Specification of sample manufacturing service

	Parameter	Design rule
Circuit formation	Conductive material	Silver ink
	Standard thickness	4 or 7 um
	Min. L/S	140 / 200 um
Resin formation	Max resin build size	120 x 60 mm
	Max resin build thickness	4 mm
	Size of print bed	120 x 120 mm
Layer to layer connection	Max layer count	5 layers
	L to L connection	Blind via hole
Part placement	Conductive material	Silver paste
	Min. electrode pitch (Peripheral)	0.5 mm
	Min. part size	0.6 x 0.3 mm

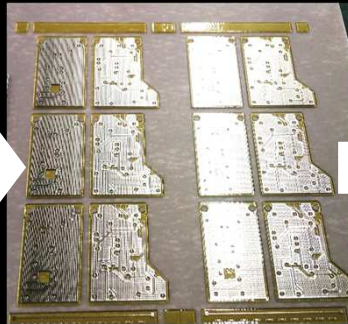
Manufacturing process flow

Core formation



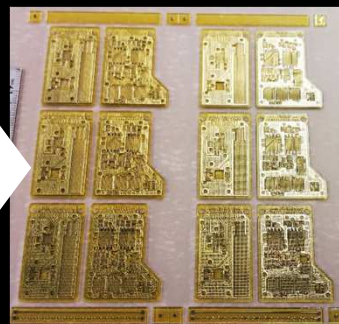
- Resin ink printing
- UV exposure

Circuit print



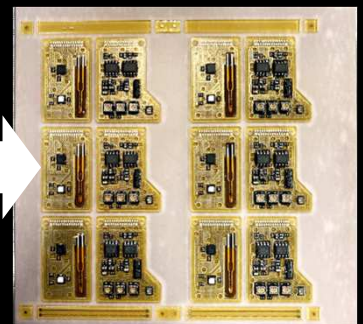
- Ag ink printing
- Drying and Sintering

Multi layer buildup



- Iteration of resin and Ag formation

Part placement

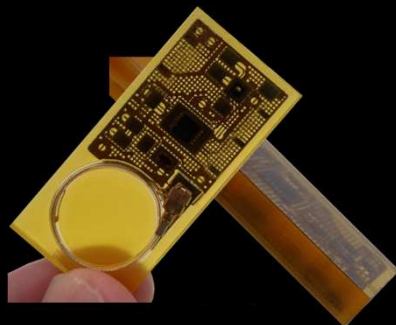


- Ag paste bump printing
- Part pick & placement
- Underfill epoxy printing
- Press curing

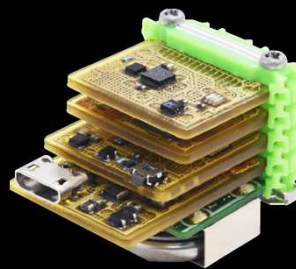
Example of manufactured samples



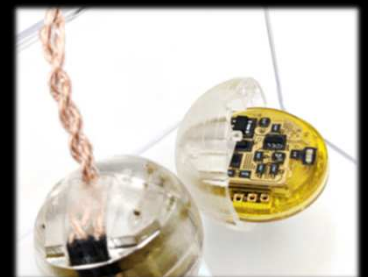
3D module



Encapsulation



Rapid PoC



Easy assembling

